

Appl. No. 10/552,540
Amdt. Dated August 30, 2007
Reply to Office Action of May 3, 2007

Attorney Docket No. 81844.0044
Customer No.: 26021

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Shigeru TANAKA, et al.
Serial No: 10/552,540
Confirmation No.: 2300
Filed: October 11, 2005
For: THERMOSETTING RESIN
COMPOSITION, MULTILAYER
BODY USING SAME, AND CIRCUIT
BOARD

Art Unit: 1714
Examiner: Patrick Dennis
Niland

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated May 3, 2007, the time for response to which is extended one month by the accompanying petition from August 3, 2007 to September 3, 2007, please amend the above-referenced application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 28 of this paper.